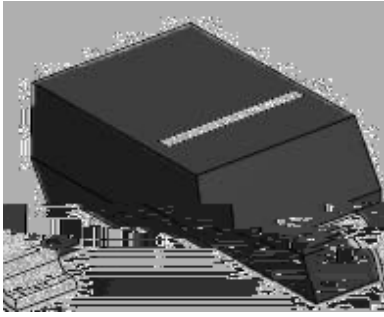


High Speed Switching Diode



Features

V_R 75V
 I_{FAV} 200mA

Typical Applications

Extreme fast switches

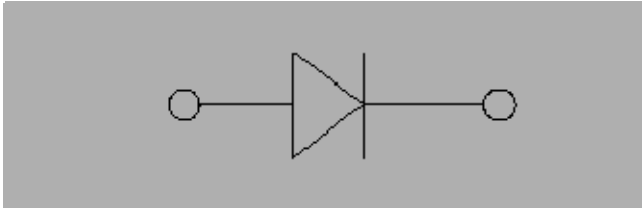
Mechanical Data

Package: SOD-323

Terminals: Tin plated leads, solderable per J-STD-002 and JESD22-B102

Polarity: Cathode line denotes the cathode end

Marking: T4



Maximum Ratings ($T_a=25$ Unless otherwise specified)

| PARAMETER | SYMBOL | UNIT | Conditions | VALUE |
|---------------------------------|------------|------|---------------|------------|
| Repetitive peak reverse voltage | V_{RRM} | V | | 75 |
| Peak forward surge current | I_{FSM} | A | $t_p=10\mu s$ | 2 |
| Average forward current | I_{FAV} | mA | | 200 |
| Power dissipation | P_{tot} | mW | | 350 |
| Thermal Resistance | R_{thJA} | /W | | 315 |
| Maximum junction temperature | T_j | | | -55 ~ +150 |
| Storage temperature range | T_{sig} | | | -55 ~ +150 |

Electrical Characteristics ($T_a=25$ Unless otherwise specified)

| PARAMETER | SYMBOL | UNIT | Conditions | Min | Typ | Max |
|---------------------------|--------|---------|------------------------------------|-----|-----|-------|
| Maximum Forward voltage | V_F | V | $I_F=1mA$ | | | 0.715 |
| | V_F | V | $I_F=10mA$ | | | 0.855 |
| | V_F | V | $I_F=50mA$ | | | 1.0 |
| | V_F | V | $I_F=150mA$ | | | 1.25 |
| Maximum Reverse current | I_R | μA | $V_R=75V$ | | | 1.0 |
| Minimum Breakdown voltage | V_R | V | $I_R=100\mu A$ | 100 | | |
| | t_r | ns | $I_F=10mA, I_{rr}=0.1I_R, R_L=100$ | | | 6 |

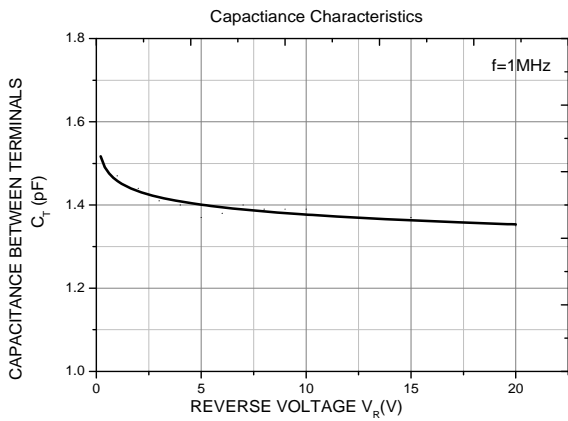
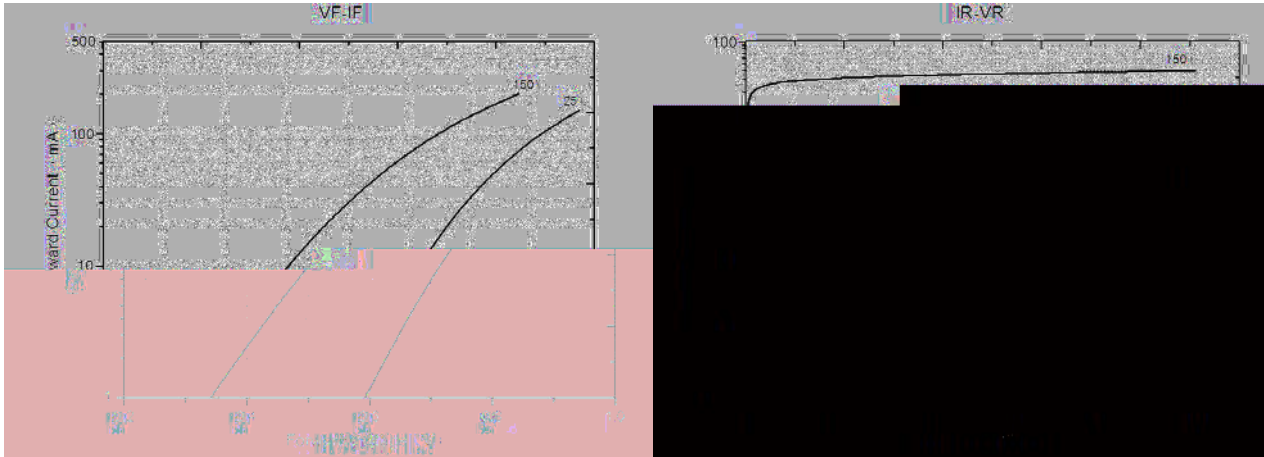


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Ordering Information (Example)

| PREFERED P/N | PACKING CODE | UNIT WEIGHT(g) | MINIMUM PACKAGE(pcs) | INNER BOX QUANTITY(pcs) | OUTER CARTON QUANTITY(pcs) | DELIVERY MODE |
|--------------|--------------|--------------------|----------------------|-------------------------|----------------------------|---------------|
| BAS16WS | F2 | Approximate 0.0048 | 3000 | 30000 | 120000 | 7" reel |

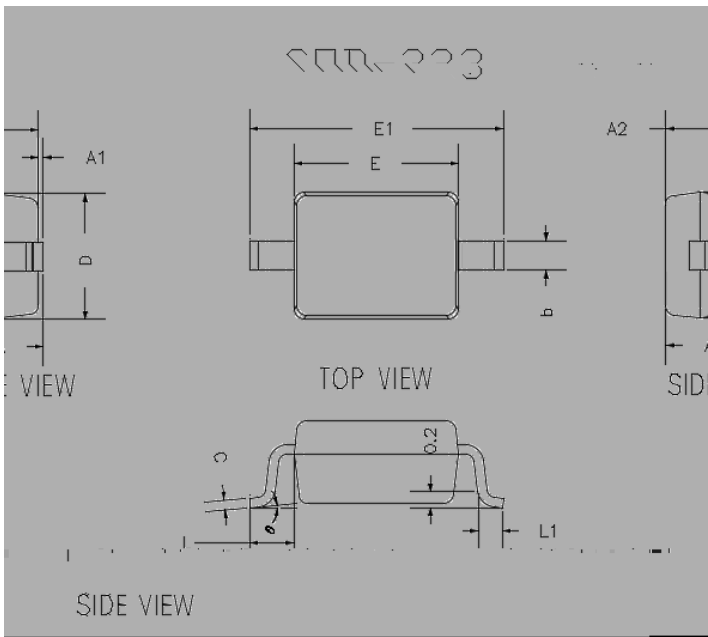
Characteristics (Typical)





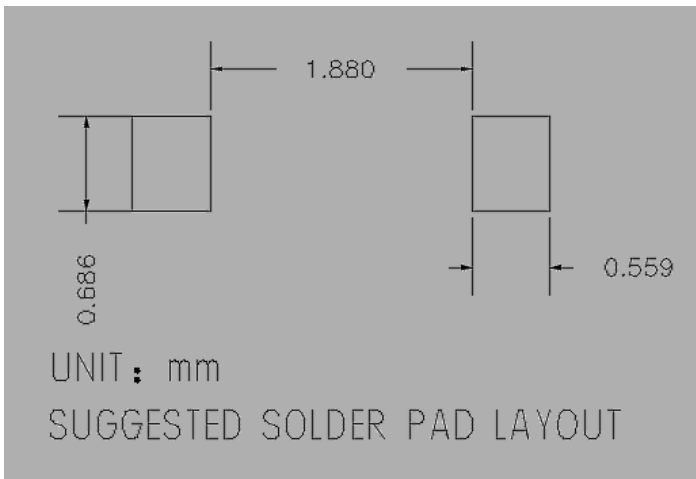
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Outline Dimensions



| DIMENSIONS | | | | |
|------------|------------|--------|-----------|--------|
| DIM | INCHES | | MM | |
| | MIN | MAX | MIN | MAX |
| A | --- | 0.0393 | --- | 1.0000 |
| A1 | 0.0000 | 0.0039 | 0.0000 | 0.1000 |
| A2 | 0.0314 | 0.0354 | 0.8000 | 0.9000 |
| b | 0.0098 | 0.0157 | 0.2500 | 0.4000 |
| D | 0.0472 | 0.0551 | 1.2000 | 1.4000 |
| E | 0.0629 | 0.0708 | 1.6000 | 1.8000 |
| E1 | 0.0984 | 0.1063 | 2.5000 | 2.7000 |
| L1 | 0.0187 TYP | | 0.475 TYP | |
| L1 | 0.0098 | 0.0157 | 0.250 | 0.400 |
| θ | 0° | 8° | 0° | 8° |

Soldering Footprint





BAS16WS

Disclaimer

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The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with